LAMINATED MATRIX COMPOSITES - A NEW CLASS OF MATERIALS

W. Jack Lackey, Elliot Pickering, Harry King, Stephen Crain, Mark Renier, and Lisa Ditter-Hoskins

George W. Woodruff School of Mechanical Engineering
Georgia Institute of Technology
Atlanta, Georgia 30332-0405

Dr. Alexander Pechenik
AFOSR / NA
801 North Randolph Street, Room 732
Arlington, Virginia 22203

A new type of composite, which consists of a reinforcement phase plus a matrix composed of many alternate thin layers of two different materials, has been prepared. CVI appears to be an appropriate process for the fabrication of this class of materials. We have successfully fabricated such a composite using the forced flow-thermal gradient CVI process. A carbon 2-D cloth preform was infiltrated with alternate layers of C and SiC having thicknesses of 0.01 to 0.5 μm. Composites containing inexpensive SiC particles or platelets rather than fibrous reinforcement were also prepared. For a fixed cycle time, layer thicknesses increased with distance from the fiber surface. Crack deflection patterns indicate that the laminated matrix may contribute to mechanical toughness. The latter half of the project emphasized the CVD of Ti₃SiC₂ which may be a useful fiber-matrix interface coating and/or matrix material. Ti₃SiC₂ was successfully deposited onto graphite substrates, and more recently on C and SiC cloth substrates. The reagent system TiCl₄-SiCl₄-CCl₄-H₂ was used.
LAMINATED MATRIX COMPOSITES - A NEW CLASS OF MATERIALS
GRANT NUMBER F49620-96-1-0321

W. Jack Lackey, Elliot Pickering, Harry King,
Stephen Crain, Mark Renier, and Lisa Ditter-Hoskins

George W. Woodruff School of Mechanical Engineering
Georgia Institute of Technology
Atlanta, Georgia 30332-0405

Introduction
It is well-known that ceramics have desirable properties—such as lightweight, high stiffness, corrosion/wear resistance, and strength retention at high temperatures. However, their brittleness limits their use in most structural applications. Metals have excellent toughness but typically suffer from loss of strength at high temperatures, excessive creep, and high density. These shortcomings have been partially overcome for ceramics and metals using fibers or whiskers as reinforcement and also in metals using platelets and particulates. For example, the toughness of SiC and carbon have been improved by reinforcement with SiC and carbon fibers. Also, SiC fibers or platelets have been used to reinforce Ti, Al, and other metals. In these prior examples, the matrix was either single phase or contained a dispersed phase.

It is also well-known that the mechanical properties of structures can be enhanced by using alternate layers of two materials. Examples of such laminated materials include Ni/Cu, Fe/Cu, ZrO2/Al2O3, SiC/C, TiC/TiN, TiC/TiB2, TiC/Ni, Al2O3/Nb, and many others. Many of these systems, particularly those with very thin layers, reveal the superlattice structure. For most structures, it is clear that the mechanical and tribological properties improve significantly as layer thicknesses decrease, often rapidly as the layer thickness approaches ~0.02 μm.

The present work was undertaken to combine the advantages of fiber or particulate reinforcement and laminated structures. The resulting composite would have a reinforcement phase and a laminated matrix. It is suggested that this new class of composites be termed “Laminated Matrix Composites” (LMC). We have shown that laminated matrix composites containing C fibers in a C+SiC matrix can be fabricated by the chemical vapor infiltration (CVI) process.1 Such a material should have improved resistance to oxidation compared to carbon-carbon. A more oxidation-resistant material might utilize SiC fibers. Even further improvement in oxidation resistance might result from the replacement of the carbon matrix layers with Ti,SiC. This ternary ceramic compound has a layered crystal structure and mechanical properties similar to graphite, but superior oxidation resistance.2,3 It has been fabricated by solid state synthesis and by CVD.6,13

We used computerized thermodynamic calculations to permit the construction of ternary deposition diagrams for the CVD of Ti,SiC. That research has been published4. Using that information plus prior knowledge5 of the CVD of Ti,SiC, we completed an experimental study of the CVD of Ti,SiC.
Over 40 preliminary CVD experiments were performed in an effort to verify the results of previous authors. Conditions for these preliminary experiments covered a wide composition range from 5-30% CCl₄, 25-55% TiCl₄, and 25-60% SiCl₄, temperatures from 1000-1400°C, and hydrogen dilutions between 10-40. Several months of experimentation resulted in deposits containing only TiC or SiC. Only after increasing hydrogen dilution above 25 was Ti₄SiC₂ finally deposited. Based on these initial results, the following statistically designed experimental study of the CVD of Ti₄SiC₂ was planned.

**Experimental Procedure**

Four reagent compositions for the present study were chosen where previous CVD of Ti₄SiC₂ was achieved. The flow rate of hydrogen was kept constant at 2000 sccm. This was done in order to limit variations in substrate temperature from experiment to experiment due the cooling effect of flowing gas, and to minimize variation in the static gas boundary layer adjacent to the substrate. Because the total hydrogen flow remained fixed while the total reagent flow varied, hydrogen dilution, α, varied from 42.1 to 32.0. The four reagent compositions were repeated at three different temperatures (1373, 1473, 1573K) for a total of twelve experiments. Pressure and run time were kept constant at 300 torr and 150 minutes, respectfully. Table 1 shows run conditions listing flow rates, pressure, run time, α, and temperature for each experiment.

The deposition apparatus was a vertical, hot-walled reactor resistively heated with a graphite heating element. The substrates were ATJ graphite cut to 20.5 x 5.1 x 58.5 mm, and suspended ~90 mm above the gas injector. The tetrachloride reagents are liquids at room temperature and were vaporized using hydrogen as the carrier gas. Each vaporizer was equipped with a thermocouple and pressure gauge. Hydrogen flow to the vaporizers was adjusted according to the partial pressures of the reagents and controlled with MKS mass flow controllers. Excess hydrogen was routed through a separate line. Actual reagent flow rates were determined by weight loss of the vaporizer from beginning to end of an experiment.

**Results**

Table 2 gives the results from the study, listing run numbers with actual flow rates, deposition temperature, deposited phases as determined by XRD and EDS, and coating thickness. Ti₄SiC₂ was never found as a single phase, even though XRD patterns for experiments at 1300°C suggest otherwise. SEM showed the microstructure of these films was quite complicated, involving co-deposition of Ti₄SiC₂ with TiC and small amounts of TiSi₂ in some cases. Ti₄SiC₂ deposits were highly textured, with the basal planes preferentially oriented perpendicular to the substrate. Calculated flow rates show this study covered reagent compositions from 19-28% CCl₄, 30-45% TiCl₄ and 32-46% SiCl₄, and hydrogen dilution from 31-44. Ti₄SiC₂ was successfully deposited over most of this composition range. At 1300°C films showed large grained, highly textured Ti₄SiC₂, while at 1100°C Ti₄SiC₂ was co-deposited with TiC. Continuous planes of TiSi₂ parallel to the substrate surface appear at 1200 and 1100°C, but were believed to be caused by fluctuations in reagent composition through the course of the experiment. Coating thickness varied from 99-215 μm. The character of the deposited films and the morphology of the Ti₄SiC₂ in the films was highly temperature-dependent.
Table 1. Run Conditions for CVD of Ti$_3$SiC$_2$

<table>
<thead>
<tr>
<th>Run Number</th>
<th>Target Flow Rates (sccm)</th>
<th>α</th>
<th>Temperature (°C)</th>
<th>Pressure (torr)</th>
<th>Time (min)</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>TiCl$_4$</td>
<td>SiCl$_4$</td>
<td>CCl$_4$</td>
<td>H$_2$</td>
<td></td>
</tr>
<tr>
<td>1,9,5</td>
<td>17.5</td>
<td>17.5</td>
<td>12.5</td>
<td>2000</td>
<td>42.1</td>
</tr>
<tr>
<td>2,10,6</td>
<td>25.0</td>
<td>17.5</td>
<td>12.5</td>
<td>2000</td>
<td>36.4</td>
</tr>
<tr>
<td>3,11,7</td>
<td>17.5</td>
<td>25.0</td>
<td>12.5</td>
<td>2000</td>
<td>36.4</td>
</tr>
<tr>
<td>4,12,8</td>
<td>25.0</td>
<td>25.0</td>
<td>12.5</td>
<td>2000</td>
<td>32.0</td>
</tr>
</tbody>
</table>

Table 2. Results from Ti$_3$SiC$_2$ CVD Study

<table>
<thead>
<tr>
<th>Run No.</th>
<th>Designation</th>
<th>Actual Flow Rates (sccm)</th>
<th>α</th>
<th>Temp (°C)</th>
<th>Phases Identified</th>
<th>Coating Thickness (μm)</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>TiCl$_4$</td>
<td>SiCl$_4$</td>
<td>CCl$_4$</td>
<td>H$_2$</td>
<td></td>
<td>With XRD and EDS</td>
</tr>
<tr>
<td>1</td>
<td>EP29</td>
<td>16.46</td>
<td>16.27</td>
<td>10.88</td>
<td>2000</td>
<td>41.9</td>
</tr>
<tr>
<td>2</td>
<td>EP23</td>
<td>21.10</td>
<td>16.60</td>
<td>10.00</td>
<td>2000</td>
<td>41.9</td>
</tr>
<tr>
<td>3</td>
<td>EP26</td>
<td>17.50</td>
<td>24.30</td>
<td>14.20</td>
<td>2000</td>
<td>35.7</td>
</tr>
<tr>
<td>4</td>
<td>EP32</td>
<td>23.32</td>
<td>23.31</td>
<td>10.78</td>
<td>2000</td>
<td>34.8</td>
</tr>
<tr>
<td>5</td>
<td>EP24</td>
<td>16.70</td>
<td>17.80</td>
<td>11.08</td>
<td>2000</td>
<td>43.8</td>
</tr>
<tr>
<td>6</td>
<td>EP31</td>
<td>24.73</td>
<td>19.26</td>
<td>15.06</td>
<td>2000</td>
<td>33.9</td>
</tr>
<tr>
<td>7</td>
<td>EP27</td>
<td>17.50</td>
<td>24.40</td>
<td>11.30</td>
<td>2000</td>
<td>37.4</td>
</tr>
<tr>
<td>8</td>
<td>EP22</td>
<td>22.92</td>
<td>22.25</td>
<td>12.73</td>
<td>2000</td>
<td>34.5</td>
</tr>
<tr>
<td>9</td>
<td>EP25</td>
<td>17.50</td>
<td>17.70</td>
<td>13.40</td>
<td>2000</td>
<td>41.1</td>
</tr>
<tr>
<td>10</td>
<td>EP19</td>
<td>24.10</td>
<td>18.73</td>
<td>11.76</td>
<td>2000</td>
<td>36.6</td>
</tr>
<tr>
<td>11</td>
<td>EP15</td>
<td>16.70</td>
<td>26.03</td>
<td>13.89</td>
<td>2000</td>
<td>35.3</td>
</tr>
<tr>
<td>12</td>
<td>EP14</td>
<td>24.26</td>
<td>24.98</td>
<td>14.09</td>
<td>2000</td>
<td>31.6</td>
</tr>
</tbody>
</table>

X-Ray Diffraction

Figure 1 shows an XRD pattern for run EP31 which was deposited at 1300°C. Only Ti$_3$SiC$_2$ peaks are evident. It is representative of two other high temperature experiments, EP24 and EP27. All show a great deal of preferred crystallographic orientation.
Microstructure

Various microstructural characteristics are evident at different temperatures. Figure 2 shows a) the surface morphology, and b) the fractured cross section of Ti$_3$SiC$_2$ grown at 1300°C. The coating is highly oriented and characterized by large, plate-like grains oriented perpendicular to the substrate. This corroborates the preferred orientation seen with x-ray diffraction. Regions of the coating appear to have the flat side of the plate parallel to the fracture surface, while other regions appear to show the plate edge on. The surface morphology is similar in appearance to the Ti$_3$SiC$_2$ coating structure reported by Goto and Hirai. The surface is an intricate pattern of grains, which are oriented in random directions. Taken together, these micrographs suggest that although the basal planes are oriented perpendicular to the substrate, there does not appear to be additional restrictions on the growth of Ti$_3$SiC$_2$. Figure 3 shows the a) surface morphology and b) fractured cross section of a coating grown at 1100°C. XRD suggests the sample is a mixture of Ti$_3$SiC$_2$ and TiC but individual phases and grains are not discernable at this magnification. Instead the coating cross section appears rather featureless. The surface appears to consist of small, nodule-like features growing on larger nodules. Compared with Figure 2, the microstructure is much finer. There is clearly a marked difference in deposition of highly oriented, large grained Ti$_3$SiC$_2$ at 1300°C and the fine grained co-deposition of TiC and Ti$_3$SiC$_2$ at 1100°C.
Polished and etched cross sections revealed more details about the microstructure of these coatings. Figure 4 is a series of micrographs taken from experiments performed at 1100°C. Figure 4a shows the cross section of an over etched sample. The vertical bands running parallel to the substrate are the result of different etch rates on the different phases.

EDS has shown these bands to be composed of Ti$_2$SiC$_2$, TiC and TiSi$_2$, again confirming data from XRD. Figure 4b was taken at higher magnification. Continuous layers of TiSi$_2$ appear early in the growth process, and are believed to be caused by fluctuations in reagent flow rates. As the carbon content of the reagent mix becomes too low, TiSi$_2$ begins to form at the leading edge of the growing surface. The remainder of the coating consists of Ti$_2$SiC$_2$ and TiC growing simultaneously, as shown in Figure 4c. The layered crystal structure is apparent in the Ti$_2$SiC$_2$ grains, identified with EDS.

Figure 4. SEM micrographs of polished and etched cross sections of films grown at 1100°C showing a) layers of TiC, Ti$_2$SiC$_2$, and TiSi$_2$ formed by differing etch rates, b) continuous TiSi$_2$ layers and TiC/Ti$_2$SiC$_2$ co-deposition, c) high resolution of Ti$_2$SiC$_2$ grains in TiC matrix, and d) lower resolution Ti$_2$SiC$_2$ grains in TiC matrix.

Surrounding these grains are regions of TiC. The EDS spectrum from the TiC shows some silicon, but not enough to suggest Ti$_2$SiC$_2$. It is not clear whether the silicon signal is due to solid solubility of silicon in TiC or due to Ti$_2$SiC$_2$ grains hidden beneath the polished surface. Finally, Figure 4d also shows the microstructure of this two phase
region at a lower magnification. The dark phase was identified with EDS as Ti₃SiC₂, while the lighter, matrix phase was identified as TiC.

Figure 5 shows a series of micrographs for 1300°C experiments. Figure 5a is the polished and etched cross section of one of these coatings. The layered structure growing perpendicular to the substrate in fan-like grains is readily apparent. A boundary layer appears between these grains and the substrate. EDS identified this boundary layer as TiC with a small amount of silicon. A similar layer appears midway through the coating, parallel to the substrate, but much thinner. It is labeled the “intermittent layer”. EDS shows this to be TiC as well. Figure 5b shows the interface between this TiC layer and Ti₃SiC₂ grains at high magnification. Notice how individual layers of the Ti₃SiC₂ grow directly into the TiC layer. The absence of a clear grain boundary between the TiC layer and Ti₃SiC₂ suggests a semi-coherent interface. Figure 5d shows the fan-like structure of Ti₃SiC₂ grains. Notice the cracks initiating in the "hilt" of the fan, and extending outward in a straight line, guided by individual layers of the grain. This demonstrates the crack deflecting properties of layered Ti₃SiC₂. These grains appear to consist of a light and a dark phase, even though the layered appearance of the structure suggests Ti₃SiC₂ alone. EDS on individual layers showed the lighter phase too silicon deficient to be Ti₃SiC₂. Instead, the grain may consist of sandwiched layers of TiC and Ti₃SiC₂.

![Figure 5. SEM micrographs of polished and etched cross sections of films grown at 1300°C showing a) TiC boundary and intermittent layers between fan-like grains of Ti₃SiC₂, b) interface between Ti₃SiC₂ and intermittent TiC layer, c) Ti₃SiC₂ grains seen with various orientation, and d) crack deflection in Ti₃SiC₂ and lamella structure of fan-like grains.](image)

Summary and Conclusions
The CVD experimental study provided interesting results. Ti₃SiC₂ was successfully deposited for only the fourth time in over twenty-five years. Nearly pure Ti₃SiC₂ was deposited at 1300°C while Ti₃SiC₂-TiC composites were co-deposited at 1100 and 1200°C. At high temperature, a TiC boundary layer formed between the coating and the substrate, and periodically a thinner TiC layer was formed between regions of Ti₃SiC₂. Also, at least some of the Ti₃SiC₂ grains formed as a lamella structure with
TiC. This would suggest that the nucleation and growth of Ti₃SiC₂ is somewhat dependent on TiC. At all temperatures, Ti₃SiC₂ showed considerable preferred orientation, in which basal planes were deposited perpendicular to the substrate. Significant effort was focused on determining the temperature dependence of this orientation. Our results showed that at least some Ti₃SiC₂ was deposited with basal planes parallel to the substrate at 1100-1200°C. Additional details of this research are available.¹⁶

Using the results as guidelines, we have recently succeeded in the deposition of Ti₃SiC₂ onto T-300 carbon cloth and Nicalon SiC cloth. The coating was highly crystalline in each case. Some deposition conditions appear to produce a coating that readily debonds from the fiber.

Acknowledgement / Disclaimer
This work was sponsored in part by the Air Force Office of Scientific Research, USAF, under Grant No. F49620-96-1-0321. The views and conclusions contained herein are those of the authors and should not be interpreted necessarily as representing the official policies or endorsements, either expressed or implied, of the Air Force Office of Scientific Research or the United States government.

References

Publications Resulting from this Research
8. Elliot Pickering, "Chemical Vapor Deposition of Ti₅SiC₂," Master of Science Thesis in Materials Science and Engineering, Georgia Institute of Technology, Atlanta, Georgia USA, June 1998.

Laminated C-SiC Matrix Composites Produced by CVI

W. Jack Lackey†
Georgia Tech Research Institute, Georgia Institute of Technology, Atlanta, Georgia 30332

Sundar Vaidyaraman†
School of Chemical Engineering, Georgia Institute of Technology, Atlanta, Georgia 30332

Karren L. More†
Oak Ridge National Laboratory, Oak Ridge, Tennessee 37830

The resulting composite would have a reinforcement phase and a laminated matrix. It is suggested that this new class of composites be termed “Laminated Matrix Composites” (LMC). Laminated structures are typically fabricated by stacking foils, followed by hot pressing or diffusion bonding, various coating processes, sedimentation, centrifuging, and electrophoresis. These processes, with the exception of CVI, do not readily lend themselves to the infiltration of fibrous or particulate preforms, although Whitehead et al. have prepared a thick-layered alumina-zirconia matrix by electrophoresis. Furthermore, several of the processes are not applicable to submicrometer thick layers, because of difficulties with handling or limitations on the size of the constituents. However, using CVI, a porous preform can be infiltrated with a laminated matrix by periodically changing the reagent stream from one type of precursor to another. In this way, many thin matrix layers may be easily deposited. Both CVD and CVI have been used to make multilayered fiber-matrix interface coatings and oxidation protection coatings for carbon and other composites. Naslain et al. have used CVI to deposit what they refer to as a hybrid matrix where the first portion of the infiltration process is accomplished using one material and the final infiltration step utilizes a second material. Similarly, we and others have prepared fiber-reinforced composites where the matrix was subdivided into three to five layers. Polymeric precursors, pitch, or CVI were used to synthesize either a C-SiC or BN-SiC matrix. Steffier and Shinavski have deposited a layered C-SiC matrix and subsequently removed the carbon layers by oxidation, thus obtaining a “layered” SiC matrix.

The approach of the present work consisted of repeating the fiber-matrix interface coating periodically throughout the matrix. That is, the vast majority of the matrix consisted of one phase, say SiC, which was partitioned into up to five thick layers by thin layers of the interface materials, i.e., carbon or BN.

The present work was undertaken with the goal of preparing a fiber-reinforced laminated matrix composite where the layers were significantly thinner than in the prior work. Accordingly, up to 80 layers as thin as 0.01 μm were used with the view that the thinner layers, as previously discussed, would enhance the mechanical properties. The two components chosen for the matrix were C and SiC with carbon fibers as the reinforcement phase. This system is of interest since the components are light, chemically compatible, and obtainable via CVI. Further, the anisotropic structure of carbon permits debonding and thus the potential for arresting the propagation of cracks, i.e., toughening.

II. Experimental Details

Laminated matrix composites (LMC) in the shape of right circular disks were fabricated using the forced flow-thermal
gradient CVI process. In this process, a pressure gradient forces the reagent stream to flow through a preform which is subjected to a temperature gradient. The details of the equipment and general experimental procedure have been explained elsewhere.24 Briefly, the preforms consisted of 40 layers of T-300 plain weave carbon cloth, 4.8 cm in diameter, oriented at 0° and 90°. These layers were stacked in a graphite preform holder and lightly compacted, giving a height of ~0.8 cm. Two types of preform holders, namely, type 2 and 3, which are described in a prior publication,24 were used. The type 2 and 3 preform holders extended 5.1 and 7.6 cm above the gas injector, respectively. The height of the preform holder influences the temperature and the temperature gradient through the preform. The temperature differences between the hot and cold sides for the type 2 and 3 preform holders were ~250° and ~150°C, respectively.

The operating conditions for the infiltration experiments are given in Table I. A thin carbon interface was deposited before the deposition of the laminated matrix. The interface was deposited by flowing 40 cm³/min of methane and 160 cm³/min of hydrogen through the preform for 20 min. The temperature of the bottom of the preform during the interface deposition was ~975°C. This step was followed by deposition of C and SiC, alternately. Carbon was deposited from a reagent mixture containing 50% propylene–50% hydrogen, and the total flow rate was 400 cm³/min. The SiC layers were deposited using 5 cm³/min of methyltrichlorosilane (MTC) and 500 cm³/min of hydrogen. The deposition time for each laminate layer was 5 min except for L-5, where each SiC layer was deposited for 10 min. Two infiltration runs (L-2 and -6) were conducted using only a carbon matrix for the purpose of comparison with the LMCs.

The temperature of the bottom of the preform during the course of depositing the laminated matrix fluctuated between 900° and 961°C. This temperature variation was caused by changing the reagent stream, thereby altering the thermal conductivity of the gas between the water-cooled gas injector and the preform. The thermal conductivity of the propylene/hydrogen mixture was lower than that of the MTS/hydrogen mixture for the concentrations used in the present work. Consequently, the temperature increased when the propylene/hydrogen mixture was used as the reagent, and the temperature decreased when the reagent was changed to MTS/hydrogen. About 60 s elapsed between ending the deposition of one layer and starting the deposition of the next layer. During this interval, hydrogen was flowed through the composite.

The apparent volume of the composite was determined using Archimedes' principle with methanol (p = 0.79 g/cm³). The open-pore volume was calculated by weighing the composite saturated with methanol. These two values were used to calculate the bulk volume. To calculate total porosity, the density of the deposited carbon and SiC were 1.9 and 3.2 g/cm³, respectively, and that the volume of carbon deposited was twice that of the SiC deposited. This latter assumption is an approximation based on observed microstructures.

An entire cross section of each composite disk was mounted in epoxy and polished. The polished sections were observed via scanning electron microscopy to permit observation of the composite microstructure. Several samples were fractured, using flexure, to observe the propagation of cracks. Transmission electron microscopy was used to more clearly observe the thinner layers and to determine the phases deposited.

### III. Results

The objective of this work was realized; laminated matrix composites containing numerous very thin layers were successfully prepared. The infiltration time, density, and porosity of the laminated matrix composites (L-1, -3, and -5), and carbon matrix composites (L-2 and -6) used as controls, are given in Table II. The infiltration time for the laminated composites was 4.5–8 h versus ~4 h for the carbon matrix composites; apparently, this is the result of SiC deposition being slower than carbon deposition for the conditions used here. The open porosity of the laminated matrix and that of the carbon matrix samples are similar, but the closed porosity values are higher for the laminated matrix composites. This indicates that the conditions used for SiC infiltration require adjustment in order to achieve similar levels of closed porosity.

Scanning electron microscopy showed that the desired laminated matrix composites were achieved in each case (Figs. 1–3). Both the C and SiC layers were generally continuous with the exception of the first few layers in sample L-3. Transmission electron microscopy and electron diffraction verified that the deposits were turbostratic carbon and crystalline SiC, as expected. The number of layers at a given location depended on the space between the fibers. In a cloth layup, as used in the present work, the distance between the fibers within a tow was 2–3 μm (micropores), and the distance between the tows was 50–100 μm (macropores). The tows became densified early in the infiltration process, and most of the infiltration time was spent on filling the macropores found between the cloth layers and tows within a cloth.24 Hence, not all layers were observed within a tow (Fig. 3). However, all the layers were observed in the matrix deposited within the macropores (Fig. 2).

As shown in Figs. 1–3, layers of C and SiC <0.5 μm in thickness were achieved. The thickness of the deposited layers generally increased with increasing distance from the fiber surface during the deposition process. The thickness of the initial layers was as small as 0.01 μm and increased to ~0.5 μm near the end of the deposition process. The increase in the deposition rate, i.e., layer thickness, with infiltration time was caused by

### Table I. Processing Conditions for Laminated Matrix Composites

<table>
<thead>
<tr>
<th>Run No.</th>
<th>Fiber type</th>
<th>Temperature of preform bottom (°C)</th>
<th>Carbon deposition time per cycle (min)</th>
<th>SiC deposition time per cycle (min)</th>
</tr>
</thead>
<tbody>
<tr>
<td>L-1</td>
<td>3</td>
<td>910–950</td>
<td>5</td>
<td>5</td>
</tr>
<tr>
<td>L-2</td>
<td>3</td>
<td>915–954</td>
<td>5</td>
<td>5</td>
</tr>
<tr>
<td>L-3</td>
<td>2</td>
<td>900–961</td>
<td>5</td>
<td>5</td>
</tr>
<tr>
<td>L-5</td>
<td>3</td>
<td>910–959</td>
<td>5</td>
<td>10</td>
</tr>
<tr>
<td>L-6</td>
<td>2</td>
<td>900–967</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

### Table II. Properties of the Infiltrated Composites

<table>
<thead>
<tr>
<th>Run No.</th>
<th>Fiber content (vol%)</th>
<th>Total No. of cycles</th>
<th>Infiltration time (h)</th>
<th>Weight gain (g)</th>
<th>Bulk density (g/cm³)</th>
<th>Total porosity (%)</th>
<th>Open porosity (%)</th>
</tr>
</thead>
<tbody>
<tr>
<td>L-1</td>
<td>50.6</td>
<td>40</td>
<td>6.67</td>
<td>12.90</td>
<td>1.672</td>
<td>16.4</td>
<td>5.94</td>
</tr>
<tr>
<td>L-2</td>
<td>49.0</td>
<td>40</td>
<td>6.25</td>
<td>11.74</td>
<td>1.658</td>
<td>11.2</td>
<td>9.2</td>
</tr>
<tr>
<td>L-3</td>
<td>56.7</td>
<td>27</td>
<td>4.50</td>
<td>14.74</td>
<td>1.700</td>
<td>13.7</td>
<td>5.56</td>
</tr>
<tr>
<td>L-5</td>
<td>51.8</td>
<td>32</td>
<td>8.00</td>
<td>12.88</td>
<td>1.647</td>
<td>17.7</td>
<td>8.90</td>
</tr>
<tr>
<td>L-6</td>
<td>50.8</td>
<td>36</td>
<td>3.60</td>
<td>13.11</td>
<td>1.692</td>
<td>7.6</td>
<td>7.57</td>
</tr>
</tbody>
</table>
reduction of reagent depletion during the infiltration process. The term "reagent depletion" refers to the reduction in concentration of the reagent as the process gas stream traverses the preform. Initially the reagent depletion was very high due to the high surface area of the preform, but since densification isolates an ever-increasing number of tows, the surface area of the preform gradually reduces. This reduction in surface area, in turn, reduces reagent depletion and thereby leads to the observed increase in layer thickness with time.

Several samples were deliberately fractured in order to observe, via SEM, the crack path. As shown in Fig. 4, evidence that the laminate layers offer resistance to crack propagation was seen. The crack shown here does not propagate in a straight line, but instead follows a tortuous path with jogs occurring from one laminate layer to an adjacent layer. Typical debonding at the fiber-matrix interface (not shown) was also observed. While these results are encouraging, extensive mechanical testing will be required to determine if the laminated matrix does indeed enhance composite toughness.

IV. Discussion

Considerable experimental investigation and/or modeling of the fracture behavior of laminated matrix composites will likely be required in order to determine optimum material combinations and layer thicknesses for maximizing mechanical performance. Questions to be answered include identifying the preferred relative elastic moduli and strengths for the matrix materials, the modulus of the matrix compared to that of the
reinforcement, and should be layers the ceramic, metallic, or one ceramic and one metallic. Also, it remains to be determined whether the laminate layers should be of equal thickness or should one type layer be thicker? Should a given type layer be of uniform thickness, or should the layers vary in thickness with distance from the reinforcement phase?

The laminated matrix composite concept offers a number of interesting options for improving performance and lowering costs. For example, if the multiple interfaces within the laminated matrix are effective in retarding crack propagation, that is, increasing toughness, then it may be possible to use particles or platelets, rather than fibers, as the reinforcement phase. If this is shown to be possible, then appreciable reduction in composite costs would result. Particles of SiC are commercially available in a variety of sizes for $1–2/lb compared to $300/lb for Nicalon SiC fiber. It may be that readily cleaved oxides, such as the β′-aluminas, magnetoplumbite, or monazite, may be appropriate materials for use as the reinforcement or as one of the matrix layers.

V. Summary

Laminated matrix composites containing fiber reinforcement and a matrix composed of alternate layers of C and SiC were successfully prepared using the forced-flow-thermal-gradient CVI process. Layer thicknesses were in the range 0.01–0.5 μm and increased with distance from the fiber surface because of a reduction of surface area as densification progressed. Nonlinear crack paths in the matrix indicated that lamination may enhance mechanical toughness.

Acknowledgments:

We appreciate the guidance of Dr. Alexander Pechenik of the Air Force Office of Scientific Research. The assistance of Michael Miller, Regina Richards, and seven diligent undergraduate mechanical engineering students who performed most of the experimentation is appreciated. We also appreciate typing and editing of the original manuscript by Virginia Myers and Joey Goddard, respectively.

References


C. Drollard, "2D-SiC/C/Si CVI Composite with a (C-SiC), Multilayered Interphase: Processing, Microstructure and Tensile Behavior at Room Temperature," Thesis, University of Bordeaux, France, June, 1993.


Chemical Vapor Deposition of Ti$_3$SiC$_2$

(Submitted for publication in Advanced Materials, 1999)

Elliot Pickering*, W. Jack Lackey**, Steven Crain*

*School of Materials Science and Engineering
**G.W. Woodruff School of Mechanical Engineering

Georgia Institute of Technology

Atlanta, Georgia 30332

ABSTRACT

Thermodynamic calculations and experiments were performed to better understand the CVD of Ti$_3$SiC$_2$. The computer program SOLGASMIX-PV was used to calculate deposition diagrams for the TiCl$_4$-SiCl$_4$-CCl$_4$-H$_2$ reagent system. The effects of hydrogen to reagent concentration, temperature, and pressure were explored with a “box” type study, surrounding a middle condition of 1300K, 760 kPa, and a hydrogen to reagent concentration ratio of 20:1. Results suggest that Ti$_3$SiC$_2$ prefers to deposit at lower hydrogen to reagent concentrations, lower temperatures, and higher pressures. An experimental study of the CVD of Ti$_3$SiC$_2$ was also conducted revealing important morphological details about deposited Ti$_3$SiC$_2$. Deposits showed a complicated microstructure consisting of various combinations of Ti$_3$SiC$_2$, TiC, and TiSi$_2$. The preferred orientation of Ti$_3$SiC$_2$ basal planes was shown to be perpendicular to the substrate, with the degree of orientation and other microstructural characteristics dependent on temperature.
KEY WORDS: Ti$_3$SiC$_2$, Thermodynamic Modeling, CVD, Microstructure, Composites

INTRODUCTION

The integration of fiber-matrix ceramic interface coatings like carbon (graphite) and hexagonal BN have resulted in improved fracture toughness and lifetime to failure for fiber-reinforced composites at low temperature.$^{1-3}$ These coatings are typically deposited by chemical vapor deposition (CVD). The success of carbon and BN was attributed to their crystal structures. Weakly bonded basal planes, when oriented parallel to the fiber reinforcement, served to deflect cracks propagating through the matrix, thus preserving the integrity of the fibers. Fiber pullout and fiber bridging mechanisms are enabled, which lead to improved mechanical properties. Unfortunately, these effects are subdued at high temperature due to oxidation susceptibility. In response, a tremendous effort by the ceramic community was launched in order to identify and synthesize high temperature, oxidation resistant alternatives. To date, oxide compounds in the monazite, magnetoplumbite, and other systems have received extensive attention.$^{4-6}$ The exploration of Ti$_3$SiC$_2$ as a fiber-matrix interface is a natural extension of this work because it has better resistance to oxidation than carbon and BN, current interface coating.$^{7,8}$

Investigation of Ti$_3$SiC$_2$ has accelerated in recent years as its properties suggested a host of possible applications. Its layered crystal structure, high temperature ductility, and parabolic oxidation resistance suggest it may be appropriate for fiber-matrix interface
applications in ceramic matrix composites. It may also be useful as the matrix or as a layer material in laminated matrix composites. The resulting "laminated matrix composite" might have enhanced fracture toughness compared to a composite containing a monolithic matrix.

The FCVI process often involves deposition over a range of temperatures, pressures, and reagent concentrations. Therefore, in order to deposit Ti$_3$SiC$_2$ by the forced flow chemical vapor infiltration (FCVI) process, a thorough understanding of the CVD of Ti$_3$SiC$_2$ must be established, including the thermodynamics and kinetics of the reaction, as well as the extent of the Ti$_3$SiC$_2$ deposition field. Since 1972 only three groups have previously published on the CVD of Ti$_3$SiC$_2$. This knowledge base is insufficient to permit the application of the FCVI process to Ti$_3$SiC$_2$. The goal of the present work, was to further that understanding by performing thermodynamic modeling of the TiCl$_4$-SiCl$_4$-CCl$_4$-H$_2$ reagent system and conducting an experimental CVD study. It is hoped that the resulting data from both modeling and experimentation together may reveal important parameters necessary for the successful CVD and CVI of Ti$_3$SiC$_2$ in future work.

**PREVIOUS CVD OF Ti$_3$SiC$_2$**

Prior CVD synthesis of Ti$_3$SiC$_2$ is summarized in Figure 1. Reagent compositions are shown on a ternary deposition diagram, along with the deposition temperature, pressure and hydrogen dilution used during these CVD studies. Nickl et al. completed
the most comprehensive study of the TiCl₄-SiCl₄-CCl₄-H₂ deposition system in 1972, experimentally determining the entire range of the ternary deposition diagram with more than 100 experiments. Nickl et al.¹⁰ report polycrystalline layers of Ti₃SiC₂ below 1200° C and single crystal, hexagonal plates above 1300° C. Goto and Hirari¹¹ reported the next successful attempt at single phase Ti₃SiC₂ deposition in 1987. Like Nickl et al., they prepared thick films of monolithic Ti₃SiC₂ using the TiCl₄-SiCl₄-CCl₄-H₂ reagent system. Deposition rates were reported at 200 μm/h. The final group to publish on the CVD of Ti₃SiC₂ was Racault et al.¹² in 1994. They used the TiCl₄-SiCl₄-CH₄-H₂ reagent system, citing the reduced thermal stability of CH₄ over CCl₄. Their work demonstrated the importance of hydrogen dilution, a parameter they called α. This was defined as the ratio of hydrogen to the total amount of Si-Ti-C containing reagents, or α = X_H₂ / (X_TiCl₄ + X_SiCl₄ + X_CH₄). This work failed to produce single phase Ti₃SiC₂ under any conditions studied, but instead Ti₃SiC₂ was co-deposited with TiSi₂ or Ti₃Si₃ and small amounts SiC and TiC. Our objectives were to explore by thermodynamic calculations and CVD experiments wider ranges of processing conditions that should be useful for FCVI. Film microstructures determined by XRD and SEM/EDS were also closely correlated with processing conditions.

THERMODYNAMIC MODELING

In the present work, deposition diagrams were calculated for the TiCl₄-SiCl₄-CCl₄-H₂ reagent system using the SOLGAS_MIX-PV computer program.¹³⁻¹⁵ SOLGAS_MIX-PV
computed equilibrium conditions for a particular chemical system given input quantities of reactants, temperature and pressure, a list of possible products (gases, liquids and solids), and corresponding enthalpy and entropy for each chemical species considered. The computer program follows several iterations until the free energy of the entire mixture is minimized. A total of 65 species were considered, 17 solids and 48 gases. There were no liquids suitable for consideration in this system. The thermodynamic data used have been previously published.16 All thermodynamic data were taken at 1300K from the JANAF tables,17 except data for the titanium silicides, Ti$_3$SiC$_2$, and Ti$_5$Si$_3$C$_x$. Titanium silicide data were obtained from Kubaschewski and Evans18 and Engqvist et al.19 and Vahlas et al.20 These papers give enthalpy, entropy, and heat capacity values for titanium silicides at 298 K. These data were applied to Kirchhoff’s Law to obtain enthalpy and entropy values at 1300K. Thermodynamic data for the two ternary phases in the Ti-Si-C system, Ti$_3$SiC$_2$ and Ti$_5$Si$_3$C$_x$, were obtained from Racault et al21 and Sambasivan.22 These papers, based on our computerized literature search, are the only source of thermodynamic data for these ternary phases. The only prior effort at thermodynamic modeling of the CVD of Ti$_3$SiC$_2$ is the work of Racault et al.21

Simulated deposition conditions (temperature, pressure, and hydrogen to reagent concentration ratio) for which deposition diagrams were calculated were chosen using a “box” type design. The middle condition of the study was 1300K, 101 kPa, and a hydrogen to reagent concentration ratio of 20:1. Temperature was varied from 1100 to 1500K. Pressure was varied from 40.0 to 203 kPa. The α parameter was varied from 10:1 to 30:1. In all, seven deposition diagrams were calculated in order to study the effects of these variables. Unlike the work for Racault et al.,21 all calculations were
based on the reagent system TiCl$_4$-SiCl$_4$-CCl$_4$-H$_2$. In order to be complete, calculations were performed over the entire range of the phase diagram. SOLGASMIX-PV was used to perform a calculation at every 5% interval across the ternary for a total of 231 calculations per diagram. This permits construction of approximate ternary deposition diagrams but does not locate all small phase fields, and thus portions of the diagram appear to violate the phase rule.

**Calculated Deposition Diagrams**

The deposition diagram for the middle condition of the study (1300K, 101 kPa, 20:1 $\alpha$ parameter) is shown in Figure 2. In addition to showing the location of each phase field, mole ratio contours are included around the single phase field for Ti$_3$SiC$_2$. These contours can be interpreted as the mole percent of Ti$_3$SiC$_2$ in the total deposit. The edges of the single phase field can be considered the 100% contour. Moving outward, the percentage of deposited Ti$_3$SiC$_2$ drops as other phases are also formed. The 80% and 50% mole ratio contours are shown for all deposition diagrams. To the left of the Ti$_3$SiC$_2$ single phase field is a two phase field consisting of Ti$_3$SiC$_2$ + Ti$_5$Si$_3$C$_x$. Above and to the right is the Ti$_3$SiC$_2$ + SiC phase field, while below and to the right is Ti$_3$SiC$_2$ + C. Located between the latter two phase fields is a three phase field where Ti$_3$SiC$_2$ + SiC + C exist in equilibrium. Directly below the Ti$_3$SiC$_2$ single phase field is the two phase field Ti$_3$SiC$_2$ + TiC. There is also a three phase region consisting of Ti$_3$SiC$_2$ + C + TiC. In the SiCl$_4$-rich corner of the deposition diagram is a two phase field with SiC + Ti$_5$Si$_3$C$_x$ and a three phase field consisting of SiC + Ti$_5$Si$_3$C$_x$ + Ti$_3$SiC$_2$. The single phase region for Ti$_3$Si$_3$C$_x$ lies along the TiCl$_4$-SiCl$_4$ side of the diagram between 0-5% CCl$_4$. Other two phase regions exist between Ti$_5$Si$_3$C$_x$ and the titanium silicides.
predicted on the edge of the diagram. The CCl₄-SiCl₄ edge of the diagram consists of separate single phase fields with C at one end and SiC at the other. Likewise TiC and C are shown along the CCl₄-TiCl₄ edge. With the exception of the 60 calculations along the edges, and a small region near the SiCl₄-rich side, Ti₃SiC₂ is predicted over the entire diagram.

Temperature Dependence

Temperature had the largest effect on Ti₃SiC₂ deposition. Temperature was varied from 1100K to 1300K (Figure 2) to 1500K (Figure 3), while pressure and the α parameter were kept at 101 kPa and 20:1, respectfully. The size of the single phase field for Ti₃SiC₂ increased dramatically at lower temperatures. This is a suspect result since Ti₃SiC₂ has been shown to be difficult to deposit as a single phase. It may indicate that either the thermodynamic data are in error or kinetics play a large role in the deposition of Ti₃SiC₂. However, the lowest deposition temperature in the literature was reported by Racault et al.₁² at 1373K, so no experimental work has been reported in this low temperature regime. Figure 3 stands in stark contrast. It suggests the Ti₃SiC₂ single phase field has shrunk significantly with a 400K increase in temperature. Because of the high temperature, the free energy of Ti₃SiC₂ is increased, rendering it less stable. This has the effect of reducing the single phase field to its smallest proportions of the entire study. At this point it is important to interject an important note about the following deposition diagrams. The single phase field for Ti₅Si₃Cx and other two phase fields along the SiCl₄-TiCl₄ edge are not shown, for simplicity, in subsequent deposition diagrams.
Pressure Dependence

Pressure is an important parameter in forced-flow CVI. Reagent gasses are passed through a fiber preform and the matrix is deposited. As the preform densifies, some of the paths for flow of reagent gas become closed and an appreciable pressure gradient develops. The downstream side of the preform is typically maintained at the initial pressure while the upstream side of the preform is exposed to increasing back pressure. With this in mind, pressure was varied from 40.0 kPa (Figure 4), to 101 kPa (Figure 2) to 203 kPa, while temperature and the $\alpha$ parameter were held constant at 1300K and 20:1. The deposition diagrams show a trend toward a larger $\text{Ti}_3\text{SiC}_2$ single phase field as deposition pressure increased. Accordingly, Figure 4 shows a smaller single phase field for $\text{Ti}_3\text{SiC}_2$. The mole ratio contours are packed tightly on the left side as $\text{Ti}_3\text{Si}_2\text{C}_x$ begins to form. Like many of the deposition diagrams in this study, the single phase field tolerates a very wide range of $\text{SiCl}_4$ and $\text{TiCl}_4$ reagent concentrations, from 5-50% and 30-95%, respectfully. $\text{CCl}_4$ is the most restrictive reagent with compositions ranging from 20-35%. Previous work of Goto and Hirai, Nickl et al., and Racault et al. all confirm the narrow range of carbon compositions, coupled with a broader range of silicon and titanium compositions.\textsuperscript{10-12} At 203 kPa, the single phase field was larger. It stretched farther upward toward richer silicon compositions, and farther to the right. This trend is encouraging for forced-flow CVI. CVD is rarely done at greater than atmospheric pressure, but the FCVI process might demand it. No previous experimental work has been done to verify this result.
Hydrogen to Reagent Ratio ($\alpha$) Dependence

The results for the hydrogen concentration parameter, $\alpha$, are surprising. It was varied from 10:1 to 20:1 to 30:1, while pressure and temperature were kept constant at 101 kPa and 1300K. The above ratios represent the number of moles of hydrogen for every mole of silicon, titanium, and carbon reagent. The deposition diagrams suggest that lower hydrogen concentrations support Ti$_3$SiC$_2$ deposition. This is contrary to the experimental work of Racault et al. who showed that increasing the hydrogen content enlarged the deposition range.$^{12}$

EXPERIMENTAL PROCEDURE

Over 40 preliminary CVD experiments were performed in an effort to verify the results of previous authors. Conditions for these preliminary experiments covered a wide composition range from 5-30% CCl$_4$, 25-55% TiCl$_4$, and 25-60% SiCl$_4$, temperatures from 1000-1400°C, and hydrogen dilutions between 10-40. These initial experiments resulted in deposits containing only TiC or SiC. Only after increasing hydrogen dilution above 25 was Ti$_3$SiC$_2$ finally deposited. Based on these initial results, the following experimental study of the CVD of Ti$_3$SiC$_2$ was planned.

Four reagent compositions for the present study were chosen in the region of the deposition diagram in Figure 1 where previous CVD of Ti$_3$SiC$_2$ was achieved. The total hydrogen flow rate was kept constant at 2000 cm$^3$/min. This was done in order to limit variations in substrate temperature from experiment to experiment due the cooling
effect of flowing gas, and to minimize variation in the static gas boundary layer adjacent to the substrate. Because the hydrogen flow remained fixed while the flow of reagent varied, hydrogen dilution, $\alpha$, varied from 42.1 to 32.0. The four reagent compositions were repeated at three different temperatures (1373, 1473, 1573K) for a total of 12 experiments. Pressure and run time were kept constant at 40.0 kPa and 150 minutes, respectfully. Table I shows run conditions listing the target flow rates, pressure, run time, $\alpha$, and temperature for each experiment. The experiments were conducted in random order.

The deposition apparatus was a vertical, hot-walled reactor resistively heated with a graphite heating element. The heating element, reaction chamber, substrate stage, and substrate were graphite. The furnace was evacuated, leak checked, and back filled with argon before each experiment. The substrates were ATJ graphite cut to 20.5 x 5.1 x 58.5 mm, and suspended $\sim$ 90 mm above the gas injector. The external reactor wall and gas injector were made of stainless steel and were water-cooled. Reactant gases were introduced through the gas injector, which in turn was supplied reagent gases through a series of 6.35 mm diameter stainless steel tubes and various 2 and 3-way valves. The tetrachloride reagents are liquids at room temperature and were vaporized using hydrogen as the carrier gas. Each vaporizer was equipped with a thermocouple and pressure gauge. Hydrogen flow to the vaporizers was adjusted according to the partial pressures of the reagents and controlled with MKS mass flow controllers. Excess hydrogen was routed through a separate line. Actual average reagent flow rates were determined by weight loss of the vaporizer from beginning to end of an experiment. Due to its very low vapor pressure, the TiCl$_4$ vaporizer was sometimes heated, and the stainless steel tubing
between it and the gas injector was always heated to avoid condensation in the lines. Mass flow controllers were calibrated through the calibration port before each experiment.

RESULTS

Table II gives the results from the study, listing run numbers with actual average flow rates, deposition temperature, deposited phases as determined by XRD and EDS, and coating thickness. Careful microscopy showed that Ti₃SiC₂ was never deposited as a single phase, even though XRD patterns for experiments at 1300°C suggest otherwise. SEM showed the microstructure of the films was quite complicated, involving co-deposition of Ti₃SiC₂ with TiC and small amounts of TiSi₂. Ti₃SiC₂ deposits were highly textured, with the basal planes preferentially oriented perpendicular to the substrate. Although XRD, SEM, and EDS showed significant amounts of Ti₃SiC₂ at 1100 and 1300°C, very little was deposited at 1200°C. Calculated flow rates show this study covered reagent compositions from 19-28% CCl₄, 30-45% TiCl₄ and 32-46% SiCl₄, and hydrogen dilution from 31-44. Ti₃SiC₂ was successfully deposited over most of this composition range. The films deposited at 1300°C showed large-grained, highly textured Ti₃SiC₂, while at 1100°C Ti₃SiC₂ was co-deposited with TiC. At 1200°C Ti₃SiC₂ deposited as a minor phase in a TiC matrix. Continuous planes of TiSi₂ parallel to the substrate surface appear at 1200 and 1100°C, but were believed to be caused by fluctuations in reagent composition through the course of the experiment.
Coating thickness varied from 99-215 μm. The following analysis shows that the character of the deposited films and the morphology of the Ti$_3$SiC$_2$ in the films was highly temperature dependent.

**X-Ray Diffraction**

Each of the films was subjected to XRD. Two XRD patterns from the study are shown in Figures 5 and 6. The peaks for each phase are labeled with the corresponding (hkl) values. Figure 5 is for run EP31, which was deposited at 1300°C. Only Ti$_3$SiC$_2$ peaks are evident; SEM showed some TiC was present, particularly at the coating-substrate interface. It is representative of two other high temperature experiments, EP24 and EP27. All show a great deal of preferred crystallographic orientation. Notice the (008) peak is totally missing in this scan, but according to the PDF card (40-1132) it should be the 100% peak. As further evidence of texture the (110) reflection is quite strong, which may be due the right angle orientation between (008) and (110) crystallographic planes. Another indication of preferred orientation is that the (107), (108), and (109) peaks are missing between 50-60° 2θ.

The pattern for EP23 is shown in Figure 6. This sample was deposited at 1100°C. It shows peaks for both Ti$_3$SiC$_2$ and TiC. The same preferred orientation is apparent in Ti$_3$SiC$_2$. The (008) peak is present, but clearly a weaker peak than (101), (104), (105) and others. The TiC peaks in these patterns do not show preferred orientation. Notice the TiC (220) peak directly overlaps the Ti$_3$SiC$_2$ (110) peak. Without knowing the
relative amounts of each phase, it is difficult to quantify how much of the peak intensity is due to which phase.

PDF Card Refinement

Several discrepancies were noted between the XRD patterns collected for this CVD study and the pattern for $\text{Ti}_3\text{SiC}_2$ recorded on the PDF card. Three peaks were consistently obtained during the course of this research that were not present on the card. Because these peaks are found in XRD patterns taken from samples prepared through different means, synthesized by different authors, and because they do not belong to other solids in the Ti-Si-C system, we concluded that the peaks belong to $\text{Ti}_3\text{SiC}_2$. The plane-spacing equation for hexagonal crystals was taken from Cullity. Using this equation and the unit cell size for $\text{Ti}_3\text{SiC}_2$, it is possible to calculate for various values of (hkl) where additional peaks might occur. Excellent agreement between the calculated and observed d-spacings, as shown in Table III, strongly suggests that these three peaks are attributed to $\text{Ti}_3\text{SiC}_2$.

Preferred Orientation of $\text{Ti}_3\text{SiC}_2$

Irrespective of deposition temperature, preferred crystallographic orientation was observed in $\text{Ti}_3\text{SiC}_2$. In an effort to quantify this, the relative intensities of peaks in collected XRD patterns were compared to the relative intensities on the PDF cards. In the case where more than one phase was deposited, the relative intensity of each peak was normalized to the strongest peak for that phase. The relative intensities of deposited phases were divided by the relative intensity from the PDF card. The ratios can be interpreted in the following manner; ratios greater than one suggest the relative intensity
for that peak was greater than that on the PDF card, while a ratio less than one suggests the relative intensity for that peak was less than that on the PDF card. Consistent variation from a ratio of 1.0 was taken as evidence of texture in the coating. A ratio of 1.0 suggests that peaks intensity was consistent with the reported intensity.

Preferred orientation was seen in Ti₃SiC₂ peaks for every condition in the study. The ratio for the (008) peak was consistently less than 1.0 at all deposition temperatures, but 0.0 for the 1300°C experiments. Intensities for (101) and (104) peaks were greater than 1.0 for 1100 and 1200°C experiments, but less than 1.0 at 1300°C. This suggests the orientation of deposited Ti₃SiC₂ changed with temperature. It can be shown that the (110) peak also changed intensity with temperature, even though the ratios were not reliable due to the complication with the overlapping (220) TiC peak. At 1300°C, the intensity of this peak was 7.69 (the ratio for EP24, EP27, and EP31 are considered reliable because Ti₃SiC₂ was the only phase detected with XRD). At lower temperatures the intensity from this peak is significantly smaller, even though the deposition of TiC added intensity.

In order to further characterize the nature of preferred orientation in Ti₃SiC₂, the ratios were analyzed statistically using regression techniques. Linear regression of ratios for specific (hkl)s were explored with respect to temperature. Much of the scatter in the data was found for experiments performed at 1200°C. While the ratios were fairly consistent at 1100 and 1300°C, the four 1200°C experiments, EP14, EP15, EP19, and EP23, showed a wide range of variation from 0.0-1.0. This wide variation was probably due to
considerable weakness in Ti$_3$SiC$_2$ peak intensities for experiments performed at 1200°C. With the exception of EP14, virtually no Ti$_3$SiC$_2$ was detected by XRD in coatings deposited at this temperature. Because very few Ti$_3$SiC$_2$ peaks appear, and the intensity of these peaks was quite small, the (hkl) ratios for EP15, EP19, and EP23 were not included in the linear regression analysis on the premise that the Ti$_3$SiC$_2$ content of these coatings was too small to provide an accurate XRD pattern. EP14 showed many Ti$_3$SiC$_2$ peaks with significant intensities and so was retained as an example of the type of Ti$_3$SiC$_2$ preferred orientation found at 1200°C.

Table V shows the resulting statistical data from the linear regression of the (008), (101), and (104) ratios against temperature for the shortened data set. Included in the table are the constants for slope and intercept along with their corresponding significance levels and the $R^2$ value for each fit. The constants apply to the equation $Y = AX + B$, where $Y$ is the (hkl) ratio, $X$ is deposition temperature in degrees centigrade and $A$ and $B$ are constants. With respect to the (008) (hkl), the significance level for the slope constant, $A$, suggests 97% confidence that temperature influences crystallographic orientation of deposited Ti$_3$SiC$_2$.

Microstructure

Various microstructural characteristics are evident at different temperatures. Figure 7 shows a) the surface morphology, and b) the fractured cross section of Ti$_3$SiC$_2$ grown at 1300°C. The coating is highly oriented and characterized by large, plate-like grains oriented perpendicular to the substrate. This corroborates the preferred orientation seen with x-ray diffraction. Some regions of the coating appear to have the flat side of the
plate parallel to the fracture surface, while other regions appear to show the plate edge on. The surface morphology is similar in appearance to the Ti$_3$SiC$_2$ coating structure reported by Goto and Hirai.\textsuperscript{11} The surface is an intricate pattern of grains, which are oriented in random directions. Taken together, these micrographs suggest that although the basal planes are oriented perpendicular to the substrate, there does not appear to be additional restrictions on the growth of Ti$_3$SiC$_2$. Figure 8 shows the a) surface morphology and b) fractured cross section of a coating grown at 1100°C. XRD suggests the sample is a mixture of Ti$_3$SiC$_2$ and TiC but individual phases and grains are not discernable at this magnification. Instead the coating cross section appears rather featureless. The surface appears to consist of small, nodule-like features growing on larger nodules. Compared with Figure 7, the microstructure is much finer. There is clearly a marked difference in deposition of highly oriented, large grained Ti$_3$SiC$_2$ at 1300°C and the fine grained co-deposition of TiC and Ti$_3$SiC$_2$ at 1100°C. Strangely, the 1200°C experiments did not yield significant amounts of Ti$_3$SiC$_2$.

Polished and etched (1H$_2$0:1HN0$_3$:1HF)$^{24}$ cross sections revealed more details about the microstructure of these coatings. Figure 9 is a series of micrographs taken from experiments performed at 1100°C. Figure 9a shows the cross section of an over etched sample. The vertical bands running parallel to the substrate are the result of different etch rates on the different phases. EDS has shown these bands to be composed of Ti$_3$SiC$_2$, TiC and TiSi$_2$, again confirming data from XRD. Figure 9b was taken at higher magnification. Continuous layers of TiSi$_2$ appear early in the growth process, and are believed to be caused by fluctuations in reagent flow rates. As the carbon content of the
reagent mix becomes too low, TiSi$_2$ begins to form at the leading edge of the growing surface. The remainder of the coating consists of Ti$_3$SiC$_2$ and TiC growing simultaneously, as shown in Figure 9c. The layered crystal structure is apparent in the Ti$_3$SiC$_2$ grains, identified with EDS. Surrounding these grains are regions of TiC. The EDS spectrum from the TiC shows some silicon, but not enough to suggest Ti$_3$SiC$_2$. It is not clear whether the silicon signal is due to solid solubility of silicon in TiC or due to Ti$_3$SiC$_2$ grains hidden beneath the polished surface. Finally, Figure 9d also shows the microstructure of this two phase region at a lower magnification. The dark phase was identified with EDS as Ti$_3$SiC$_2$, while the lighter, matrix phase was identified as TiC.

Figure 10 shows a series of micrographs for 1300°C experiments. Figure 10a is the polished and etched cross section of one of these coatings. The layered structure growing perpendicular to the substrate in fan-like grains is readily apparent. A boundary layer appears between these grains and the substrate. EDS identified this boundary layer as TiC with a small amount of silicon. There is the possibility that the TiC layer formed as a result of reaction with the graphite substrate. A similar layer appears midway through the coating, parallel to the substrate, but much thinner. It is labeled the "intermittent layer". EDS shows this to be TiC as well. Figure 10b shows the interface between this TiC layer and Ti$_3$SiC$_2$ grains at high magnification. Notice how individual layers of the Ti$_3$SiC$_2$ grow directly into the TiC layer. The absence of a clear grain boundary between the TiC layer and Ti$_3$SiC$_2$ suggests a semi-coherent interface. Figure 10c shows the fan-like structure of Ti$_3$SiC$_2$ grains. Notice the cracks initiating in the "hilt" of the fan, and extending outward in a straight line, guided by individual layers of the grain. This demonstrates the crack deflecting properties of
layered Ti$_3$SiC$_2$. These grains appear to consist of a light and a dark phase, even though the layered appearance of the structure suggests Ti$_3$SiC$_2$ alone. EDS on individual layers showed the lighter phase too silicon deficient to be Ti$_3$SiC$_2$. Instead, the grain may consist of sandwiched layers of TiC and Ti$_3$SiC$_2$. This may correspond to the lamella TiC/Ti$_3$SiC$_2$ structure first described by Nickl et al.$^{10}$ Referring again to Figure 10a, the presence of TiC is further evidenced by a distinct demarcation approximately three fifths of the way through the coating, below which a great deal of the lighter phase, believed to be TiC, exists. Above this line, there is much less of the light phase. It is from this upper region that XRD data are collected, and perhaps one reason TiC is not seen with XRD. Figure 10d shows Ti$_3$SiC$_2$ grains in this region near the surface of the coating. The layered nature of the plate-like crystals is unmistakable, with some grains oriented edge on and some oriented flat to the field of view. EDS from these regions confirmed the presence of Ti$_3$SiC$_2$.

**SUMMARY AND CONCLUSIONS**

Thermodynamic modeling has shown that the extent of the Ti$_3$SiC$_2$ single-phase field is highly dependent on process conditions. Although there was minimal agreement between calculated results and experimental results, thermodynamics alone may not be sufficient to completely model the system. Instead, the disagreement suggested that kinetics might play an important part in the CVD of Ti$_3$SiC$_2$. Furthermore, calculated deposition diagrams represent the minimum free energy of the system, given sufficient time to react. At lower temperatures, it is possible that more time is needed to reach that minimum free
energy, while at higher temperatures the kinetics of the reaction may be sufficiently fast to reach equilibrium. Calculated deposition diagrams showed Ti$_3$SiC$_2$ preferred to deposit at lower temperatures, lower hydrogen dilution, and higher pressures. This study, to the best of our knowledge, was the most complete thermodynamic modeling of the TiCl$_4$-SiCl$_4$-CCl$_4$-H$_2$ reagent system to date.

The CVD experimental study also provided interesting results. Ti$_3$SiC$_2$ was successfully deposited for only the fourth time in over 25 years. Although the microstructures of deposited films were too complicated to permit extraction of kinetic data, the composition and morphology of these films were determined over a wide temperature range by extensive use of XRD, EDS, and SEM. Nearly pure Ti$_3$SiC$_2$ was deposited at 1300°C while Ti$_3$SiC$_2$-TiC composites were co-deposited at 1100 and 1200°C. At high temperature, a TiC boundary layer formed between the coating and the substrate, and periodically a thinner TiC layer was formed between regions of Ti$_3$SiC$_2$. Future thermodynamic calculations might include excess carbon as an input condition in order to determine to what extent, if any, a carbon substrate would influence the deposition diagrams. Such results would be pertinent to the early stage of deposition. Also, at least some of the Ti$_3$SiC$_2$ grains formed as a lamella structure with TiC. This would suggest that the nucleation and growth of Ti$_3$SiC$_2$ is somewhat dependent on TiC, which might be the kinetic hindrance unaccounted for by thermodynamic calculations. At all temperatures, Ti$_3$SiC$_2$ showed considerable preferred orientation, in which basal planes were deposited perpendicular to the substrate. Significant effort was focused on determining the temperature dependence of this orientation. Some Ti$_3$SiC$_2$ was deposited with basal planes parallel to the substrate at 1100-1200°C.
ACKNOWLEDGEMENTS

We appreciate the financial support and technical guidance provided by Dr. Alexander Pechenik of the Air Force Office of Scientific Research, Dr. Liselotte Schioler of the National Science Foundation, and First Lieutenant Kenneth A. Self of Wright Laboratories.

REFERENCES


LIST OF TABLES

Table I. Run Conditions for CVD of Ti$_3$SiC$_2$

Table II. Results from Ti$_3$SiC$_2$ CVD Study

Table III. Indices and d-spacing for observed Ti$_3$SiC$_2$ peaks not found on the PDF card

Table IV. Linear regression statistics for (hkl) ratios against temperature
Table I. Run Conditions for CVD of Ti$_3$SiC$_2$

<table>
<thead>
<tr>
<th>Run Number</th>
<th>Target Flow Rates (cm$^3$/min)</th>
<th>$\alpha$</th>
<th>Temperature ($^\circ$C)</th>
<th>Pressure (kPa)</th>
<th>Time (min)</th>
</tr>
</thead>
<tbody>
<tr>
<td>1,9,5</td>
<td>TiCl$_4$ 17.5  SiCl$_4$ 17.5  CCl$_4$ 12.5  H$_2$ 2000</td>
<td>42.1</td>
<td>1100,1200,1300</td>
<td>40.0</td>
<td>150</td>
</tr>
<tr>
<td>2,10,6</td>
<td>TiCl$_4$ 25.0  SiCl$_4$ 17.5  CCl$_4$ 12.5  H$_2$ 2000</td>
<td>36.4</td>
<td>1100,1200,1300</td>
<td>40.0</td>
<td>150</td>
</tr>
<tr>
<td>3,11,7</td>
<td>TiCl$_4$ 17.5  SiCl$_4$ 25.0  CCl$_4$ 12.5  H$_2$ 2000</td>
<td>36.4</td>
<td>1100,1200,1300</td>
<td>40.0</td>
<td>150</td>
</tr>
<tr>
<td>4,12,8</td>
<td>TiCl$_4$ 25.0  SiCl$_4$ 25.0  CCl$_4$ 12.5  H$_2$ 2000</td>
<td>32.0</td>
<td>1100,1200,1300</td>
<td>40.0</td>
<td>150</td>
</tr>
</tbody>
</table>
Table IV. Linear regression statistics for (hkl) ratios against temperature

<table>
<thead>
<tr>
<th>(hkl)</th>
<th>A (slope)</th>
<th></th>
<th>B (intercept)</th>
<th></th>
<th>R²</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Constant</td>
<td>Sig. level</td>
<td>Constant</td>
<td>Sig. level</td>
<td></td>
</tr>
<tr>
<td>(008)</td>
<td>-9.5454E-04</td>
<td>0.0276*</td>
<td>1.2770</td>
<td>0.0175</td>
<td>58.2%</td>
</tr>
<tr>
<td>(101)</td>
<td>2.1381E-03</td>
<td>0.0857</td>
<td>-0.1691</td>
<td>0.8960</td>
<td>41.3%</td>
</tr>
<tr>
<td>(104)</td>
<td>-4.0418E-03</td>
<td>0.0008</td>
<td>5.8209</td>
<td>0.0003</td>
<td>86.7%</td>
</tr>
</tbody>
</table>

*Indicates 97% confidence that temperature influences crystallographic orientation.
LIST OF FIGURES

Figure 1. Review of the CVD of Ti₃SiC₂.

Figure 2. Calculated deposition diagram for the middle condition in the study.

Figure 3. Calculated deposition diagram for the conditions 1500K, 101 kPa, α = 20:1. The dramatic change in the single phase field of Ti₃SiC₂ demonstrates the sensitivity of its thermodynamic data to deposition temperature.

Figure 4. Calculated deposition diagram for the conditions 1300K, 40.0 kPa, and α = 20:1.

Figure 5. XRD pattern for EP31 deposited at 1300°C. Only Ti₃SiC₂ peaks are evident and peaks from basal planes show little intensity. This suggests highly textured Ti₃SiC₂.

Figure 6. XRD pattern for EP23 deposited at 1100°C. The pattern shows TiC and Ti₃SiC₂ peaks, with significant intensity from both phases.

Figure 7. a) Surface morphology and b) cross section of coatings grown at 1300°C.

Figure 8. a) Surface morphology and b) cross section of coatings grown at 1100°C.

Figure 9. SEM micrographs of polished and etched cross sections of films grown at 1100°C showing a) layers of TiC, Ti₃SiC₂, and TiSi₂ formed by differing etch rates, b) continuous TiSi₂ layers and TiC/Ti₃SiC₂ co-deposition, c) high resolution of Ti₃SiC₂ grains in TiC matrix, and d) lower resolution Ti₃SiC₂ grains in TiC matrix.

Figure 10. SEM micrographs of polished and etched cross sections of films grown at 1300°C showing a) TiC boundary and intermittent layers between fan-like grains of Ti₃SiC₂, b) interface between Ti₃SiC₂ and intermittent TiC layer, c) Ti₃SiC₂ grains seen with various orientation, and d) crack deflection in Ti₃SiC₂ and lamella structure of fan-like grains.
Figure 1. Review of the CVD of Ti$_3$SiC$_2$
Figure 2. Calculated deposition diagram for the middle condition in the study.
Figure 3. Calculated deposition diagram for the conditions 1500K, 101 kPa, $\alpha = 20:1$. The dramatic change in the single phase field of Ti$_3$SiC$_2$ demonstrates the sensitivity of its thermodynamic data to deposition temperature.
Figure 4. Calculated deposition diagram for the conditions 1300K, 40 kPa, and $\alpha = 20:1$. 
Figure 5. XRD pattern for EP31 deposited at 1300°C. Only Ti$_3$SiC$_2$ peaks are evident and peaks from basal planes show little intensity. This suggests highly textured Ti$_3$SiC$_2$. 
Figure 6. XRD pattern for EP23 deposited at 1100°C. The pattern shows TiC and Ti$_3$SiC$_2$ peaks, with significant intensity from both phases.
Figure 7. a) Surface morphology and b) cross section of coatings grown at 1300°C.
Figure 8. a) Surface morphology and b) cross section of coatings grown at 1100°C.
Figure 9. SEM micrographs of polished and etched cross sections of films grown at 1100°C showing a) layers of TiC, Ti$_3$SiC$_2$, and TiSi$_2$ formed by differing etch rates, b) continuous TiSi$_2$ layers and TiC/Ti$_3$SiC$_2$ co-deposition, c) high resolution of Ti$_3$SiC$_2$ grains in TiC matrix, and d) lower resolution Ti$_3$SiC$_2$ grains in TiC matrix.
Figure 10. SEM micrographs of polished and etched cross sections of films grown at 1300°C showing a) TiC boundary and intermittent layers between fan-like grains of Ti$_3$SiC$_2$, b) interface between Ti$_3$SiC$_2$ and intermittent TiC layer, c) Ti$_3$SiC$_2$ grains seen with various orientation, and d) crack deflection in Ti$_3$SiC$_2$ and lamella structure of fan-like grains.